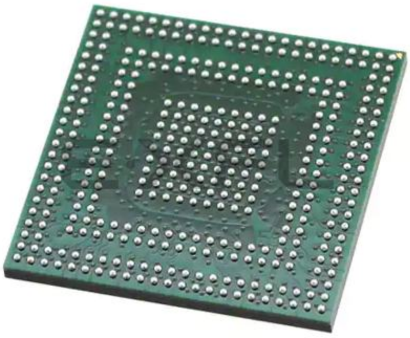


Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	PowerPC e300c3
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	133MHz
Co-Processors/DSP	Communications; QUICC Engine
RAM Controllers	DDR2
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100Mbps (3)
SATA	-
USB	USB 2.0 (1)
Voltage - I/O	1.8V, 3.3V
Operating Temperature	0°C ~ 105°C (TA)
Security Features	-
Package / Case	369-LFBGA
Supplier Device Package	369-PBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/ppc8306vmabdca

1 Overview

The MPC8306 incorporates the e300c3 (MPC603e-based) core built on Power Architecture® technology, which includes 16 Kbytes of each L1 instruction and data caches, dual integer units, and on-chip memory management units (MMUs). The MPC8306 also includes two DMA engines and a 16-bit DDR2 memory controller.

A new communications complex based on QUICC Engine technology forms the heart of the networking capability of the MPC8306. The QUICC Engine block contains several peripheral controllers and a 32-bit RISC controller. Protocol support is provided by the main workhorses of the device—the unified communication controllers (UCCs). A block diagram of the MPC8306 is shown in the following figure.

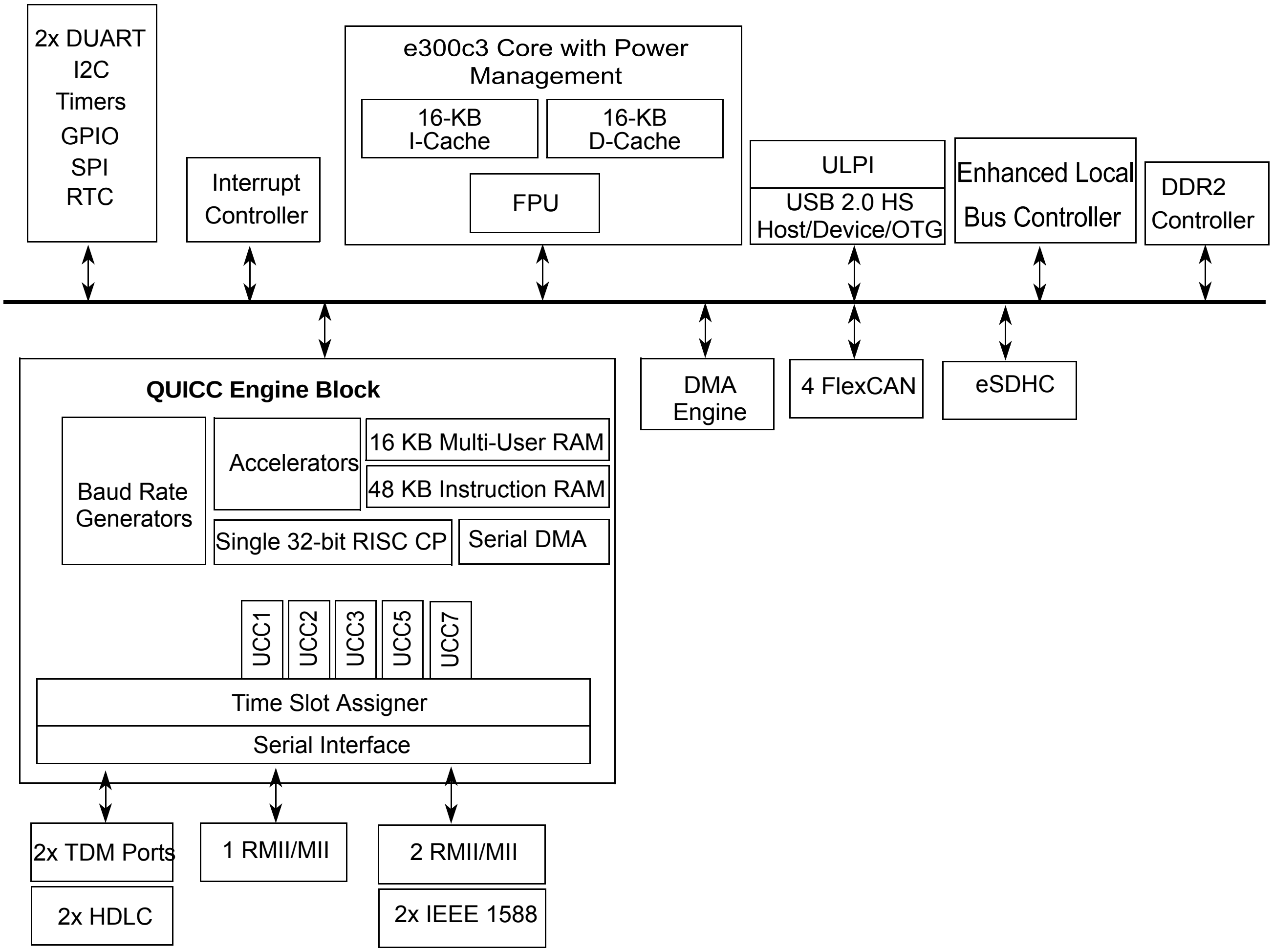


Figure 1. MPC8306 Block Diagram

Each of the five UCCs can support a variety of communication protocols such as 10/100 Mbps MII/RMII Ethernet, IEEE-1588, HDLC and TDM.

    - Asynchronous HDLC (bit rate up to 2 Mbps)
    - Two TDM interfaces supporting up to 128 QUICC multichannel controller channels, each running at 64 kbps

  For more information on QUICC Engine sub-modules, see *QUICC Engine Block Reference Manual with Protocol Interworking*.

- DDR SDRAM memory controller
  - Programmable timing supporting DDR2 SDRAM
  - Integrated SDRAM clock generation
  - 16-bit data interface, up to 266-MHz data rate
  - 14 address lines
  - The following SDRAM configurations are supported:
    - Up to two physical banks (chip selects), 256-Mbyte per chip select for 16 bit data interface.
    - 64-Mbit to 2-Gbit devices with x8/x16 data ports (no direct x4 support)
    - One 16-bit device or two 8-bit devices on a 16-bit bus,
  - Support for up to 16 simultaneous open pages for DDR2
  - One clock pair to support up to 4 DRAM devices
  - Supports auto refresh
  - On-the-fly power management using CKE
- Enhanced local bus controller (eLBC)
  - Multiplexed 26-bit address and 8-/16-bit data operating at up to 66 MHz
  - Eight chip selects supporting eight external slaves
    - Four chip selects dedicated
    - Four chip selects offered as multiplexed option
  - Supports boot from parallel NOR Flash and parallel NAND Flash
  - Supports programmable clock ratio dividers
  - Up to eight-beat burst transfers
  - 16- and 8-bit ports, separate $\overline{\text{LWE}}$ for each 8 bit
  - Three protocol engines available on a per chip select basis:
    - General-purpose chip select machine (GPCM)
    - Three user programmable machines (UPMs)
    - NAND Flash control machine (FCM)
  - Variable memory block sizes for FCM, GPCM, and UPM mode
  - Default boot ROM chip select with configurable bus width (8 or 16)
  - Provides two Write Enable signals to allow single byte write access to external 16-bit eLBC slave devices
- Integrated programmable interrupt controller (IPIC)
  - Functional and programming compatibility with the MPC8260 interrupt controller
  - Support for external and internal discrete interrupt sources

The following table provides the PLL lock times.

Table 10. PLL Lock Times

Parameter/Condition	Min	Max	Unit	Note
PLL lock times	—	100	µs	—

5.1 Reset Signals DC Electrical Characteristics

The following table provides the DC electrical characteristics for the MPC8306 reset signals mentioned in Table 9.

Table 11. Reset Signals DC Electrical Characteristics

Characteristic	Symbol	Condition	Min	Max	Unit	Note
Output high voltage	V_{OH}	I_{OH} = –6.0 mA	2.4	—	V	1
Output low voltage	V_{OL}	I_{OL} = 6.0 mA	—	0.5	V	1
Output low voltage	V_{OL}	I_{OL} = 3.2 mA	—	0.4	V	1
Input high voltage	V_{IH}	—	2.0	OV_{DD} + 0.3	V	1
Input low voltage	V_{IL}	—	–0.3	0.8	V	—
Input current	I_{IN}	$0 V \le V_{IN} \le OV_{DD}$	—	±5	µA	—

Note:
1. This specification applies when operating from 3.3 V supply.

6 DDR2 SDRAM

This section describes the DC and AC electrical specifications for the DDR2 SDRAM interface of the MPC8306. Note that DDR2 SDRAM is GV_{DD}(typ) = 1.8 V.

6.1 DDR2 SDRAM DC Electrical Characteristics

The following table provides the recommended operating conditions for the DDR2 SDRAM component(s) of the MPC8306 when GV_{DD}(typ) = 1.8 V.

Table 12. DDR2 SDRAM DC Electrical Characteristics for GV_{DD}(typ) = 1.8 V

Parameter/Condition	Symbol	Min	Max	Unit	Note
I/O supply voltage	GV_{DD}	1.7	1.9	V	1
I/O reference voltage	MVREF	0.49 × GV_{DD}	0.51 × GV_{DD}	V	2
I/O termination voltage	V_{TT}	MVREF – 0.04	MVREF + 0.04	V	3
Input high voltage	V_{IH}	MVREF+ 0.125	GV_{DD} + 0.3	V	—
Input low voltage	V_{IL}	–0.3	MVREF – 0.125	V	—
Output leakage current	I_{OZ}	–9.9	9.9	µA	4

Table 12. DDR2 SDRAM DC Electrical Characteristics for GV_{DD}(typ) = 1.8 V (continued)

Parameter/Condition	Symbol	Min	Max	Unit	Note
Output high current (V_{OUT} = 1.35 V)	I_{OH}	–13.4	—	mA	—
Output low current (V_{OUT} = 0.280 V)	I_{OL}	13.4	—	mA	—

Notes:

1. GV_{DD} is expected to be within 50 mV of the DRAM GV_{DD} at all times.
2. MVREF is expected to be equal to 0.5 × GV_{DD}, and to track GV_{DD} DC variations as measured at the receiver. Peak-to-peak noise on MVREF may not exceed ±2% of the DC value.
3. V_{TT} is not applied directly to the device. It is the supply to which far end signal termination is made and is expected to be equal to MVREF. This rail should track variations in the DC level of MVREF.
4. Output leakage is measured with all outputs disabled, $0 V \leq V_{OUT} \leq GV_{DD}$.

The following table provides the DDR2 capacitance when GV_{DD}(typ) = 1.8 V.

Table 13. DDR2 SDRAM Capacitance for GV_{DD}(typ) = 1.8 V

Parameter/Condition	Symbol	Min	Max	Unit	Note
Input/output capacitance: DQ, DQS	C_{IO}	6	8	pF	1
Delta input/output capacitance: DQ, DQS	C_{DIO}	—	0.5	pF	1

Note:

1. This parameter is sampled. GV_{DD} = 1.8 V ± 0.100 V, f = 1 MHz, T_A = 25 °C, $V_{OUT} = GV_{DD} \div 2$, V_{OUT} (peak-to-peak) = 0.2 V.

6.2 DDR2 SDRAM AC Electrical Characteristics

This section provides the AC electrical characteristics for the DDR2 SDRAM interface.

6.2.1 DDR2 SDRAM Input AC Timing Specifications

This table provides the input AC timing specifications for the DDR2 SDRAM (GV_{DD}(typ) = 1.8 V).

Table 14. DDR2 SDRAM Input AC Timing Specifications for 1.8-V Interface

At recommended operating conditions with GV_{DD} of 1.8 V± 100mV.

Parameter	Symbol	Min	Max	Unit	Note
AC input low voltage	V_{IL}	—	MVREF – 0.25	V	—
AC input high voltage	V_{IH}	MVREF + 0.25	—	V	—

The following table provides the input AC timing specifications for the DDR2 SDRAM interface.

Table 15. DDR2 SDRAM Input AC Timing Specifications

At recommended operating conditions with GV_{DD} of 1.8V ± 100mV.

Parameter	Symbol	Min	Max	Unit	Note
Controller skew for MDQS—MDQ/MDM	t_{CISKEW}			ps	1, 2

The following figure shows the DDR SDRAM output timing for the MCK to MDQS skew measurement (t_{DDKHMH}).

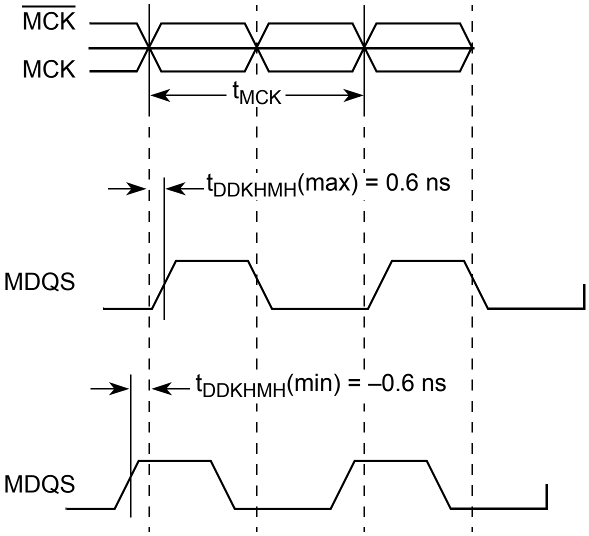


Figure 5. Timing Diagram for t_{DDKHMH}

The following figure shows the DDR2 SDRAM output timing diagram.

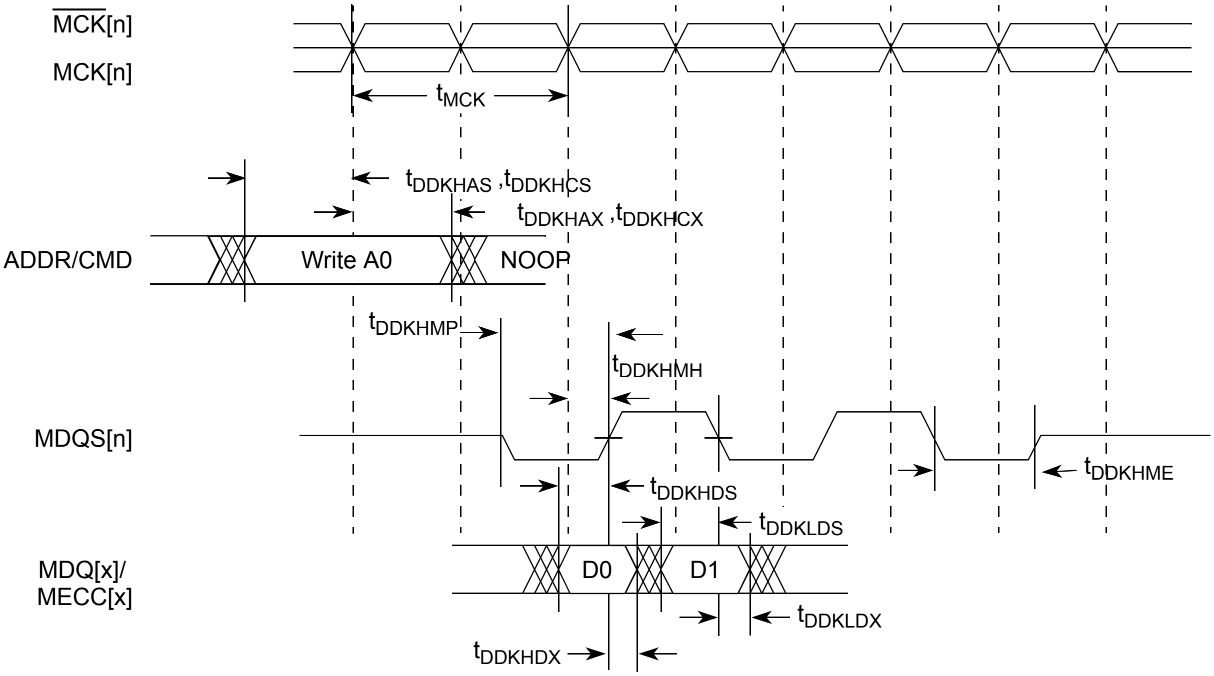


Figure 6. DDR2 SDRAM Output Timing Diagram

The following figure shows the RMII transmit AC timing diagram.

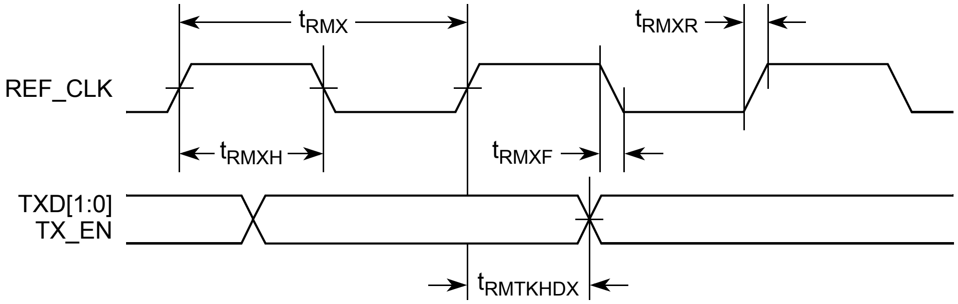


Figure 15. RMII Transmit AC Timing Diagram

8.2.2.2 RMII Receive AC Timing Specifications

The following table provides the RMII receive AC timing specifications.

Table 23. RMII Receive AC Timing Specifications

At recommended operating conditions with OV_{DD} of 3.3 V ± 300mV.

Parameter/Condition	Symbol[1]	Min	Typical	Max	Unit
REF_CLK clock period	t_{RMX}	—	20	—	ns
REF_CLK duty cycle	t_{RMXH}/t_{RMX}	35	—	65	%
RXD[1:0], CRS_DV, RX_ER setup time to REF_CLK	$t_{RMRDVKH}$	4.0	—	—	ns
RXD[1:0], CRS_DV, RX_ER hold time to REF_CLK	$t_{RMRDXKH}$	2.0	—	—	ns
REF_CLK clock rise V_{IL}(min) to V_{IH}(max)	t_{RMXR}	1.0	—	4.0	ns
REF_CLK clock fall time V_{IH}(max) to V_{IL}(min)	t_{RMXF}	1.0	—	4.0	ns

Note:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first three letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, $t_{RMRDVKH}$ symbolizes RMII receive timing (RMR) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{RMX} clock reference (K) going to the high (H) state or setup time. Also, $t_{RMRDXKL}$ symbolizes RMII receive timing (RMR) with respect to the time data input signals (D) went invalid (X) relative to the t_{RMX} clock reference (K) going to the low (L) state or hold time. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For example, the subscript of t_{RMX} represents the RMII (RM) reference (X) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).

10.1 HDLC DC Electrical Characteristics

The following table provides the DC electrical characteristics for the MPC8306 HDLC protocol.

Table 30. HDLC DC Electrical Characteristics

Characteristic	Symbol	Condition	Min	Max	Unit
Output high voltage	V_{OH}	I_{OH} = –2.0 mA	2.4	—	V
Output low voltage	V_{OL}	I_{OL} = 3.2 mA	—	0.5	V
Input high voltage	V_{IH}	—	2.0	OV_{DD} + 0.3	V
Input low voltage	V_{IL}	—	–0.3	0.8	V
Input current	I_{IN}	$0 V \le V_{IN} \le OV_{DD}$	—	±5	μA

10.2 HDLC AC Timing Specifications

The following table provides the input and output AC timing specifications for HDLC protocol.

Table 31. HDLC AC Timing Specifications[1]

Characteristic	Symbol[2]	Min	Max	Unit
Outputs—Internal clock delay	t_{HIKHOV}	0	9	ns
Outputs—External clock delay	t_{HEKHOV}	1	12	ns
Outputs—Internal clock high impedance	t_{HIKHOX}	0	5.5	ns
Outputs—External clock high impedance	t_{HEKHOX}	1	8	ns
Inputs—Internal clock input setup time	t_{HIIVKH}	9	—	ns
Inputs—External clock input setup time	t_{HEIVKH}	4	—	ns
Inputs—Internal clock input hold time	t_{HIIXKH}	0	—	ns
Inputs—External clock input hold time	t_{HEIXKH}	1	—	ns

Notes:

1. Output specifications are measured from the 50% level of the rising edge of QE_CLK_IN to the 50% level of the signal. Timings are measured at the pin.
2. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{HIKHOX} symbolizes the outputs internal timing (HI) for the time t_{serial} memory clock reference (K) goes from the high state (H) until outputs (O) are invalid (X).

The following figure provides the AC test load.

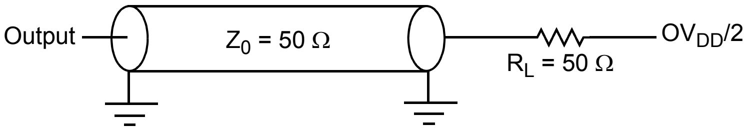


Figure 22. AC Test Load

11 USB

11.1 USB Controller

This section provides the AC and DC electrical specifications for the USB (ULPI) interface.

11.1.1 USB DC Electrical Characteristics

The following table provides the DC electrical characteristics for the USB interface.

Table 32. USB DC Electrical Characteristics

Parameter	Symbol	Min	Max	Unit
High-level input voltage	V_{IH}	2.0	OV_{DD} + 0.3	V
Low-level input voltage	V_{IL}	–0.3	0.8	V
Input current	I_{IN}	—	±5	μA
High-level output voltage, I_{OH} = –100 μA	V_{OH}	OV_{DD} – 0.2	—	V
Low-level output voltage, I_{OL} = 100 μA	V_{OL}	—	0.2	V

11.1.2 USB AC Electrical Specifications

The following table describes the general timing parameters of the USB interface.

Table 33. USB General Timing Parameters

Parameter	Symbol[1]	Min	Max	Unit	Note
USB clock cycle time	t_{USCK}	15	—	ns	—
Input setup to USB clock—all inputs	t_{USIVKH}	4	—	ns	—
input hold to USB clock—all inputs	t_{USIXKH}	1	—	ns	—
USB clock to output valid—all outputs (except USBDR_STP_USBDR_STP)	t_{USKHOV}	—	7	ns	—
USB clock to output valid—USBDR_STP	t_{USKHOV}	—	7.5	ns	—
Output hold from USB clock—all outputs	t_{USKHOX}	2	—	ns	—

Note:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{USIXKH} symbolizes USB timing (USB) for the input (I) to go invalid (X) with respect to the time the USB clock reference (K) goes high (H). Also, t_{USKHOX} symbolizes us timing (USB) for the USB clock reference (K) to go high (H), with respect to the output (O) going invalid (X) or output hold time.

The following figures provide the AC test load and signals for the USB, respectively.

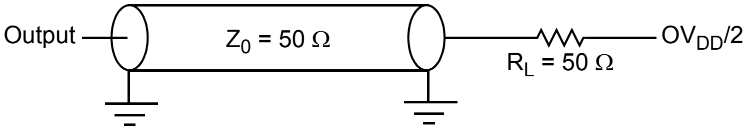


Figure 25. USB AC Test Load

12 DUART

This section describes the DC and AC electrical specifications for the DUART interface of the MPC8306.

12.1 DUART DC Electrical Characteristics

The following table provides the DC electrical characteristics for the DUART interface of the MPC8306.

Table 34. DUART DC Electrical Characteristics

Parameter	Symbol	Min	Max	Unit
High-level input voltage	V_{IH}	2	$OV_{DD} + 0.3$	V
Low-level input voltage OV_{DD}	V_{IL}	–0.3	0.8	V
High-level output voltage, $I_{OH} = –100\ \mu A$	V_{OH}	$OV_{DD} – 0.2$	—	V
Low-level output voltage, $I_{OL} = 100\ \mu A$	V_{OL}	—	0.2	V
Input current ($0\ V \leq V_{IN} \leq OV_{DD}$)[1]	I_{IN}	—	±5	μA

Note:

1. Note that the symbol V_{IN}, in this case, represents the OV_{IN} symbol referenced in Table 1 and Table 2.

12.2 DUART AC Electrical Specifications

The following table provides the AC timing parameters for the DUART interface of the MPC8306.

Table 35. DUART AC Timing Specifications

Parameter	Value	Unit	Note
Minimum baud rate	256	baud	—
Maximum baud rate	>1,000,000	baud	1
Oversample rate	16	—	2

Notes:

1. Actual attainable baud rate is limited by the latency of interrupt processing.
2. The middle of a start bit is detected as the 8th sampled 0 after the 1-to-0 transition of the start bit. Subsequent bit values are sampled each 16th sample.

Table 41. I^2C AC Electrical Specifications (continued)

All values refer to V_{IH} (min) and V_{IL} (max) levels (see Table 40).

Parameter	Symbol[1]	Min	Max	Unit
Fall time of both SDA and SCL signals	t_{I2CF}	$20 + 0.1 C_B$[4]	300	ns
Setup time for STOP condition	t_{I2PVKH}	0.6	—	µs
Bus free time between a STOP and START condition	t_{I2KHDX}	1.3	—	µs
Noise margin at the LOW level for each connected device (including hysteresis)	V_{NL}	$0.1 \times OV_{DD}$	—	V
Noise margin at the HIGH level for each connected device (including hysteresis)	V_{NH}	$0.2 \times OV_{DD}$	—	V

Notes:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{I2DVKH} symbolizes I^2C timing (I2) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{I2C} clock reference (K) going to the high (H) state or setup time. Also, t_{I2SXKL} symbolizes I^2C timing (I2) for the time that the data with respect to the start condition (S) went invalid (X) relative to the t_{I2C} clock reference (K) going to the low (L) state or hold time. Also, t_{I2PVKH} symbolizes I^2C timing (I2) for the time that the data with respect to the stop condition (P) reaching the valid state (V) relative to the t_{I2C} clock reference (K) going to the high (H) state or setup time. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).
2. MPC8306 provides a hold time of at least 300 ns for the SDA signal (referred to the V_{IH}(min) of the SCL signal) to bridge the undefined region of the falling edge of SCL.
3. The maximum t_{I2DVKL} has only to be met if the device does not stretch the LOW period (t_{I2CL}) of the SCL signal.
4. C_B = capacitance of one bus line in pF.

The following figure provides the AC test load for the I^2C.

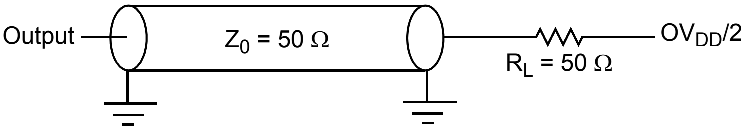


Figure 29. I^2C AC Test Load

The following figure shows the AC timing diagram for the I^2C bus.

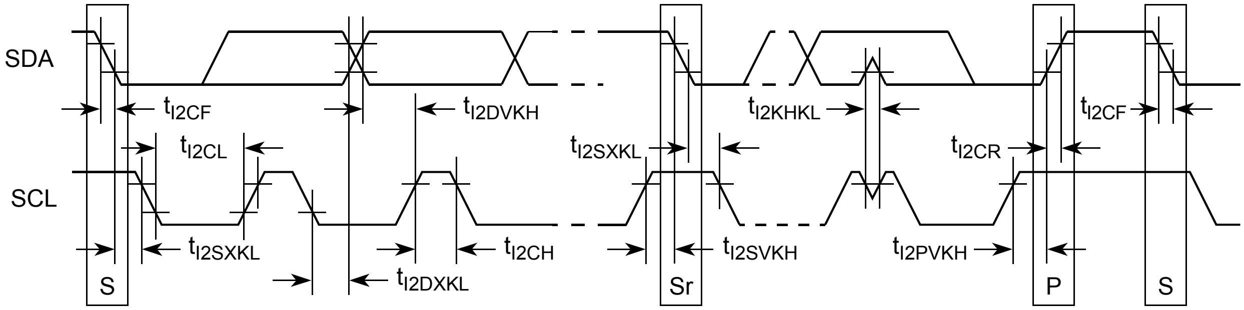


Figure 30. I^2C Bus AC Timing Diagram

Table 48. SPI DC Electrical Characteristics

Characteristic	Symbol	Condition	Min	Max	Unit
Output high voltage	V_{OH}	I_{OH} = –6.0 mA	2.4	—	V
Output low voltage	V_{OL}	I_{OL} = 6.0 mA	—	0.5	V
Output low voltage	V_{OL}	I_{OL} = 3.2 mA	—	0.4	V
Input high voltage	V_{IH}	—	2.0	OV_{DD} + 0.3	V
Input low voltage	V_{IL}	—	–0.3	0.8	V
Input current	I_{IN}	$0 V \le V_{IN} \le OV_{DD}$	—	±5	μA

19.2 SPI AC Timing Specifications

The following table and provide the SPI input and output AC timing specifications.

Table 49. SPI AC Timing Specifications[1]

Characteristic	Symbol[2]	Min	Max	Unit
SPI outputs—Master mode (internal clock) delay	t_{NIKHOV}	0.5	6	ns
SPI outputs—Slave mode (external clock) delay	t_{NEKHOV}	2	8	ns
SPI inputs—Master mode (internal clock) input setup time	t_{NIIVKH}	6	—	ns
SPI inputs—Master mode (internal clock) input hold time	t_{NIIXKH}	0	—	ns
SPI inputs—Slave mode (external clock) input setup time	t_{NEIVKH}	4	—	ns
SPI inputs—Slave mode (external clock) input hold time	t_{NEIXKH}	2	—	ns

Notes:

1. Output specifications are measured from the 50% level of the rising edge of SPICLK to the 50% level of the signal. Timings are measured at the pin.
2. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{NIKHOV} symbolizes the NMSI outputs internal timing (NI) for the time t_{SPI} memory clock reference (K) goes from the high state (H) until outputs (O) are valid (V).
3. All units of output delay must be enabled for 8306 output port spimosi (SPI Master Mode)
4. delay units must not be enabled for Slave Mode.

The following figure provides the AC test load for the SPI.

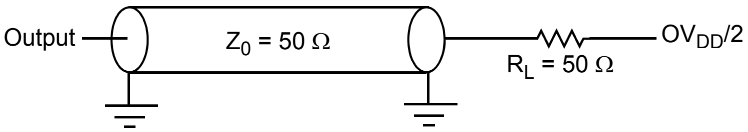
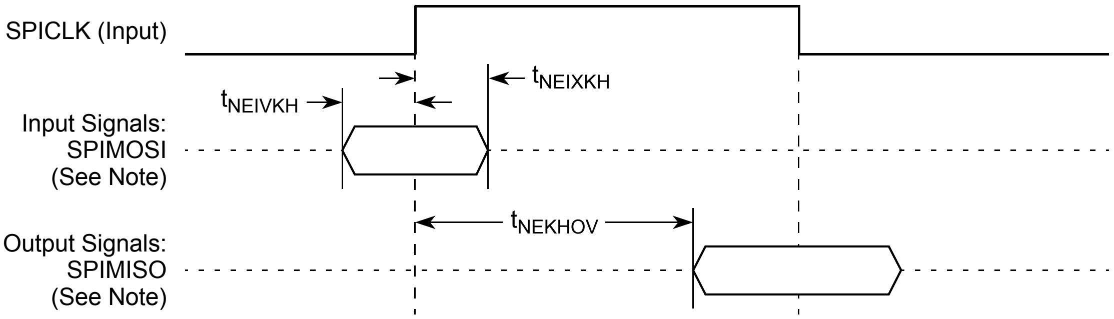


Figure 33. SPI AC Test Load

Figure 34 and Figure 35 represent the AC timing from Table 49. Note that although the specifications generally reference the rising edge of the clock, these AC timing diagrams also apply when the falling edge is the active edge.

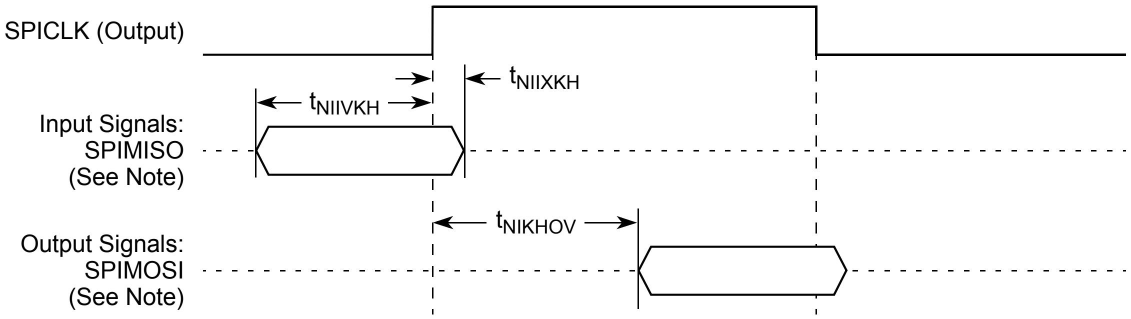
The following figure shows the SPI timing in slave mode (external clock).



Note: The clock edge is selectable on SPI.

Figure 34. SPI AC Timing in Slave Mode (External Clock) Diagram

The following figure shows the SPI timing in master mode (internal clock).



Note: The clock edge is selectable on SPI.

Figure 35. SPI AC Timing in Master Mode (Internal Clock) Diagram

20 JTAG

This section describes the DC and AC electrical specifications for the IEEE Std. 1149.1™ (JTAG) interface of the MPC8306.

20.1 JTAG DC Electrical Characteristics

The following table provides the DC electrical characteristics for the IEEE Std. 1149.1 (JTAG) interface of the MPC8306.

Table 50. JTAG Interface DC Electrical Characteristics

Characteristic	Symbol	Condition	Min	Max	Unit
Output high voltage	V_{OH}	I_{OH} = –6.0 mA	2.4	—	V
Output low voltage	V_{OL}	I_{OL} = 6.0 mA	—	0.5	V
Output low voltage	V_{OL}	I_{OL} = 3.2 mA	—	0.4	V

21.3 Pinout Listings

Following table shows the pin list of the MPC8306.

Table 52. MPC8306 Pinout Listing

Signal	Package Pin Number	Pin Type	Power Supply	Notes
DDR Memory Controller Interface				
MEMC_MDQ[0]	W5	IO	GV_{DD}	—
MEMC_MDQ[1]	V4	IO	GV_{DD}	—
MEMC_MDQ[2]	Y4	IO	GV_{DD}	—
MEMC_MDQ[3]	AB1	IO	GV_{DD}	—
MEMC_MDQ[4]	AA1	IO	GV_{DD}	—
MEMC_MDQ[5]	Y2	IO	GV_{DD}	—
MEMC_MDQ[6]	Y1	IO	GV_{DD}	—
MEMC_MDQ[7]	W2	IO	GV_{DD}	—
MEMC_MDQ[8]	G2	IO	GV_{DD}	—
MEMC_MDQ[9]	G1	IO	GV_{DD}	—
MEMC_MDQ[10]	F1	IO	GV_{DD}	—
MEMC_MDQ[11]	E2	IO	GV_{DD}	—
MEMC_MDQ[12]	E1	IO	GV_{DD}	—
MEMC_MDQ[13]	E4	IO	GV_{DD}	—
MEMC_MDQ[14]	F4	IO	GV_{DD}	—
MEMC_MDQ[15]	D1	IO	GV_{DD}	—
MEMC_MDM[0]	AB2	O	GV_{DD}	—
MEMC_MDM[1]	G4	O	GV_{DD}	—
MEMC_MDQS[0]	V5	IO	GV_{DD}	—
MEMC_MDQS[1]	F5	IO	GV_{DD}	—
MEMC_MBA[0]	L2	O	GV_{DD}	—
MEMC_MBA[1]	L1	O	GV_{DD}	—
MEMC_MBA[2]	R4	O	GV_{DD}	—
MEMC_MA[0]	M1	O	GV_{DD}	—
MEMC_MA[1]	M4	O	GV_{DD}	—
MEMC_MA[2]	N1	O	GV_{DD}	—
MEMC_MA[3]	N2	O	GV_{DD}	—
MEMC_MA[4]	P1	O	GV_{DD}	—
MEMC_MA[5]	N4	O	GV_{DD}	—
MEMC_MA[6]	P2	O	GV_{DD}	—
MEMC_MA[7]	R1	O	GV_{DD}	—

Table 52. MPC8306 Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
USBDR_TXDRXD[7]/GPIO[37]/QE_BRG[11]	Y5	IO	OV_{DD}	—
DUART				
UART1_SOUT[1]/LSRCID4/LCS_B[4]	C23	O	OV_{DD}	—
UART1_SIN[1]/LDVAL/LCS_B[5]	F19	IO	OV_{DD}	—
UART1_SOUT[2]/UART1_RTS_B1/LCS_B[6]	D23	O	OV_{DD}	—
UART1_SIN[2]/UART1_CTS_B[1]/LCS_B[7]	D22	IO	OV_{DD}	—
Interrupts				
IRQ_B0_MCP_IN_B/CE_PI_0	E20	IO	OV_{DD}	—
IRQ_B1/MCP_OUT_B	E23	IO	OV_{DD}	—
IRQ_B2/CKSTOP_OUT_B	E22	IO	OV_{DD}	—
IRQ_B3/CKSTOP_IN_B	F20	I	OV_{DD}	—
I2C / SPI				
IIC_SDA1	G20	IO	OV_{DD}	2
IIC_SCL1	J20	IO	OV_{DD}	2
LCLK1/IIC_SCL2/CKSTOP_IN_B	H20	IO	OV_{DD}	2
SPISEL_BOOT/IIC_SDA2/CKSTOP_OUT_B	F23	O	OV_{DD}	2
SPIMOSI/LSRCID[2]	G22	IO	OV_{DD}	—
SPIMISO/LSRCID[3]	K20	IO	OV_{DD}	—
SPICLK/LSRCID[0]	G23	IO	OV_{DD}	—
SPISEL/LSRCID[1]	H22	I	OV_{DD}	—
FEC Management				
FEC_MDC	H23	O	OV_{DD}	—
FEC_MDIO	L20	IO	OV_{DD}	—
FEC1/GTM/GPIO				
FEC1_COL/GTM1_TIN[1]/GPIO[16]	AB20	IO	OV_{DD}	—
FEC1_CRS/GTM1_TGATE1_B/GPIO[17]	AC21	IO	OV_{DD}	—
FEC1_RX_CLK/GPIO[18]	Y17	IO	OV_{DD}	—
FEC1_RX_DV/GTM1_TIN[2]/GPIO[19]	Y18	IO	OV_{DD}	—
FEC1_RX_ER/GTM1_TGATE[2]_B/GPIO[20]	AB19	IO	OV_{DD}	—
FEC1_RXD0/GPIO[21]	AC20	IO	OV_{DD}	—
FEC1_RXD1/GTM1_TIN[3]/GPIO[22]	AC19	IO	OV_{DD}	—
FEC1_RXD2/GTM1_TGATE[3]_B/GPIO[23]	AC18	IO	OV_{DD}	—
FEC1_RXD3/GPIO[24]	AB17	IO	OV_{DD}	—
FEC1_TX_CLK/GTM1_TIN4/GPIO[25]	Y15	IO	OV_{DD}	—
FEC1_TX_EN/GTM1_TGATE[4]_B/GPIO[26]	Y16	IO	OV_{DD}	—

In addition, some of the internal units may be required to be shut off or operate at lower frequency than the *csb_clk* frequency. These units have a default clock ratio that can be configured by a memory mapped register after the device comes out of reset.

The following table specifies which units have a configurable clock frequency. For detailed description, refer to the "System Clock Control Register (SCCR)" section in the *MPC8306 PowerQUICC II Pro Integrated Communications Processor Family Reference Manual*.

Table 53. Configurable Clock Units

Unit	Default Frequency	Options
I2C,SDHC, USB, DMA Complex	*csb_clk*	Off, csb_clk, *csb_clk*/2, *csb_clk*/3

NOTE

> Setting the clock ratio of these units must be performed prior to any access to them.

The following table provides the maximum operating frequencies for the MPC8306 MAPBGA under recommended operating conditions (see Table 2).

Table 54. Operating Frequencies for MAPBGA

Characteristic[1]	Max Operating Frequency	Unit
e300 core frequency (*core_clk*)	266	MHz
Coherent system bus frequency (*csb_clk*)	133	MHz
QUICC Engine frequency (*qe_clk*)	233	MHz
DDR2 memory bus frequency (MCLK)[2]	167	MHz
Local bus frequency (LCLK*n*)[3]	66	MHz

Notes:

1. The SYS_CLK_IN frequency, RCWL[SPMF], and RCWL[COREPLL] settings must be chosen such that the resulting csb_clk, MCLK, LCLK, and core_clk frequencies do not exceed their respective maximum or minimum operating frequencies.
2. The DDR2 data rate is 2× the DDR2 memory bus frequency.
3. The local bus frequency is 1/2, 1/4, or 1/8 of the lb_clk frequency (depending on LCRR[CLKDIV]) which is in turn 1× or 2× the csb_clk frequency (depending on RCWL[LBCM]).

22.2 System PLL Configuration

The system PLL is controlled by the RCWL[SPMF] parameter. Table 55 shows the multiplication factor encodings for the system PLL.

NOTE

> System PLL VCO frequency = 2 × (CSB frequency) × (System PLL VCO divider). The VCO divider needs to be set properly so that the System PLL VCO frequency is in the range of 450–750 MHz.

As described in Section 22, "Clocking," the LBCM, DDRCM, and SPMF parameters in the reset configuration word low select the ratio between the primary clock input (*SYS_CLK_IN)* and the internal

Table 57. e300 Core PLL Configuration (continued)

RCWL[COREPLL]			*core_clk* : *csb_clk* Ratio	VCO Divider
0-1	2-5	6		
00	0001	1	1.5:1	÷ 2
01	0001	1	1.5:1	÷ 4
10	0001	1	1.5:1	÷ 8
11	0001	1	1.5:1	÷ 8
00	0010	0	2:1	÷ 2
01	0010	0	2:1	÷ 4
10	0010	0	2:1	÷ 8
11	0010	0	2:1	÷ 8
00	0010	1	2.5:1	÷ 2
01	0010	1	2.5:1	÷ 4
10	0010	1	2.5:1	÷ 8
11	0010	1	2.5:1	÷ 8
00	0011	0	3:1	÷ 2
01	0011	0	3:1	÷ 4
10	0011	0	3:1	÷ 8
11	0011	0	3:1	÷ 8

NOTE

Core VCO frequency = core frequency × VCO divider. The VCO divider (RCWL[COREPLL[0:1]]), must be set properly so that the core VCO frequency is in the range of 400–800 MHz.

22.4 QUICC Engine PLL Configuration

The QUICC Engine PLL is controlled by the RCWL[CEPMF] and RCWL[CEPDF] parameters. The following table shows the multiplication factor encodings for the QUICC Engine PLL.

Table 58. QUICC Engine PLL Multiplication Factors

RCWL[CEPMF]	RCWL[CEPDF]	QUICC Engine PLL Multiplication Factor = RCWL[CEPMF]/ (1 + RCWL[CEPDF)
00000–00001	0	Reserved
00010	0	× 2
00011	0	× 3
00100	0	× 4
00101	0	× 5
00110	0	× 6

lifetime of the package. Recommended maximum force on the top of the package is 10 lb (4.5 kg) force. If an adhesive attachment is planned, the adhesive should be intended for attachment to painted or plastic surfaces and its performance verified under the application requirements.

23.2.1 Experimental Determination of the Junction Temperature with a Heat Sink

When heat sink is used, the junction temperature is determined from a thermocouple inserted at the interface between the case of the package and the interface material. A clearance slot or hole is normally required in the heat sink. Minimizing the size of the clearance is important to minimize the change in thermal performance caused by removing part of the thermal interface to the heat sink. Because of the experimental difficulties with this technique, many engineers measure the heat sink temperature and then back calculate the case temperature using a separate measurement of the thermal resistance of the interface.

From this case temperature, the junction temperature is determined from the junction-to-case thermal resistance using the following equation:

$$T_J = T_C + (R_{\theta JC} \times P_D) \qquad \text{Eqn. 5}$$

where:

T_C = case temperature of the package (°C)
$R_{\theta JC}$ = junction-to-case thermal resistance (°C/W)
P_D = power dissipation (W)

24 System Design Information

This section provides electrical and thermal design recommendations for successful application of the MPC8306.

24.1 System Clocking

The MPC8306 includes three PLLs.

- The system PLL (AV_{DD2}) generates the system clock from the externally supplied SYS_CLK_IN input. The frequency ratio between the system and SYS_CLK_IN is selected using the system PLL ratio configuration bits as described in Section 22.2, “System PLL Configuration.”
- The e300 core PLL (AV_{DD3}) generates the core clock as a slave to the system clock. The frequency ratio between the e300 core clock and the system clock is selected using the e300 PLL ratio configuration bits as described in Section 22.3, “Core PLL Configuration.”
- The QUICC Engine PLL (AV_{DD1}) which uses the same reference as the system PLL. The QUICC Engine block generates or uses external sources for all required serial interface clocks.

24.2 PLL Power Supply Filtering

Each of the PLLs listed above is provided with power through independent power supply pins. The voltage level at each $AV_{DD}n$ pin should always be equivalent to V_{DD}, and preferably these voltages are derived directly from V_{DD} through a low frequency filter scheme such as the following.

There are a number of ways to reliably provide power to the PLLs, but the recommended solution is to provide independent filter circuits as illustrated in Figure 44, one to each of the three AV_{DD} pins. By providing independent filters to each PLL the opportunity to cause noise injection from one PLL to the other is reduced.

This circuit is intended to filter noise in the PLLs resonant frequency range from a 500 kHz to 10 MHz range. It should be built with surface mount capacitors with minimum effective series inductance (ESL). Consistent with the recommendations of Dr. Howard Johnson in *High Speed Digital Design: A Handbook of Black Magic* (Prentice Hall, 1993), multiple small capacitors of equal value are recommended over a single large value capacitor.

Each circuit should be placed as close as possible to the specific AV_{DD} pin being supplied to minimize noise coupled from nearby circuits. It should be possible to route directly from the capacitors to the AV_{DD} pin, which is on the periphery of package, without the inductance of vias.

The following figure shows the PLL power supply filter circuit.

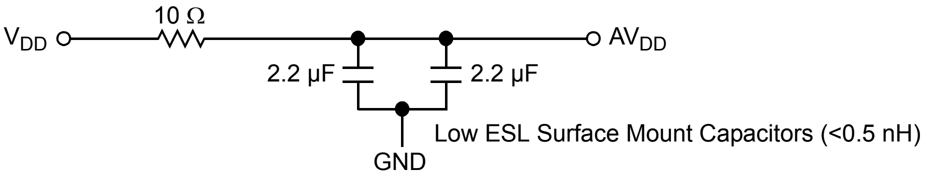


Figure 44. PLL Power Supply Filter Circuit

24.3 Decoupling Recommendations

Due to large address and data buses, and high operating frequencies, the MPC8306 can generate transient power surges and high frequency noise in its power supply, especially while driving large capacitive loads. This noise must be prevented from reaching other components in the MPC8306 system, and MPC8306 itself requires a clean, tightly regulated source of power. Therefore, it is recommended that the system designer place at least one decoupling capacitor at each V_{DD}, OV_{DD}, and GV_{DD} pins of the MPC8306. These decoupling capacitors should receive their power from separate V_{DD}, OV_{DD}, GV_{DD}, and GND power planes in the PCB, utilizing short traces to minimize inductance. Capacitors may be placed directly under the device using a standard escape pattern. Others may surround the part.

These capacitors should have a value of 0.01 or 0.1 µF. Only ceramic SMT (surface mount technology) capacitors should be used to minimize lead inductance, preferably 0402 or 0603 sizes.

In addition, it is recommended that there be several bulk storage capacitors distributed around the PCB, feeding the V_{DD}, OV_{DD}, and GV_{DD} planes, to enable quick recharging of the smaller chip capacitors. These bulk capacitors should have a low ESR (equivalent series resistance) rating to ensure the quick response time necessary. They should also be connected to the power and ground planes through two vias

The following table summarizes the signal impedance targets. The driver impedance is targeted at minimum V_{DD}, nominal OV_{DD}, 105°C.

Table 62. Impedance Characteristics

Impedance	Local Bus, Ethernet, DUART, Control, Configuration and Power Management	DDR DRAM	Symbol	Unit
R_N	42 Target	20 Target	Z_0	Ω
R_P	42 Target	20 Target	Z_0	Ω
Differential	NA	NA	Z_{DIFF}	Ω

Note: Nominal supply voltages. See Table 1, T_j = 105°C.

24.5 Configuration Pin Multiplexing

The MPC8306 provides the user with power-on configuration options which can be set through the use of external pull-up or pull-down resistors of 4.7 kΩ on certain output pins (Refer to the “Reset, Clocking and Initialization” of *MPC8306S PowerQUICC II Pro Integrated Communications Processor Family Reference Manual*). These pins are generally used as output only pins in normal operation.

While $\overline{\text{HRESET}}$ is asserted however, these pins are treated as inputs. The value presented on these pins while $\overline{\text{HRESET}}$ is asserted, is latched when $\overline{\text{HRESET}}$ deasserts, at which time the input receiver is disabled and the I/O circuit takes on its normal function. Careful board layout with stubless connections to these pull-up/pull-down resistors coupled with the large value of the pull-up/pull-down resistor should minimize the disruption of signal quality or speed for output pins thus configured.

25 Ordering Information

This section presents ordering information for the devices discussed in this document, and it shows an example of how the parts are marked. Ordering information for the devices fully covered by this document is provided in Section 25.1, “Part Numbers Fully Addressed by This Document.”

25.1 Part Numbers Fully Addressed by This Document

The following table provides the Freescale part numbering nomenclature for the MPC8306 family. Note that the individual part numbers correspond to a maximum processor core frequency. For available frequencies, contact your local Freescale sales office. In addition to the maximum processor core frequency, the part numbering scheme also includes the maximum effective DDR memory speed and QUICC Engine bus frequency. Each part number also contains a revision code which refers to the die mask revision number.

26 Document Revision History

The following table provides a revision history for this document.

Table 65. Document Revision History

Rev. No.	Date	Substantive Change(s)
3	12/2014	• In Table 20 an Table 21, V_{IL}(min) is replaced with V_{IL}(max) and V_{IH}(max) is replaced with V_{IL}(min) • Removed following signals from Table 52: – FEC1_TMR_TX_ESFD – FEC1_TMR_RX_ESFD – FEC2_TMR_TX_ESFD – FEC2_TMR_RX_ESFD • Updated following signal names in Table 52: – LGPL[0] to LGPL[0]/LFCLE – LGPL[1] to LGPL[1]/LFALE – LGPL[2] to LGPL[2]/LOE_B/LFRE_B – LGPL[3] to LGPL[3]/LFWP_B – LGPL[4] to LGPL[4]/LGTA_B/LUPWAIT/LFRB_B – LWE_B[0] to LWE_B[0]/LFWE_B[0]/LBS_B[0] – LWE_B[1] to LWE_B[1]/LBS_B[1]
2	09/2011	• Added Power numbers for core frequency of 333 MHz in Table 5. • Added new PLL configurations as per new core frequency in Table 60. • Added AF to indicate 333 MHz in Table 63.
1	06/2011	• Updated QE frequency in Table 5. • Updated QUICC Engine frequency from 200 MHz to 233 MHz in Table 54. • Updated CEMF and CEDF as per new QE frequency in Table 60. • In Part Nomenclature field for QUICC Engine frequency, C now denotes 233 MHz. Updated Table 63. • Added SPISEL_BOOT in MPC8306 Pin out Listing Table 52. • Corrected SPISEL Pin Type in Table 52.
0	03/2011	Initial Release